ON Semiconductor

FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16840

Generic Copy

Issue Date: 11-Apr-2012

TITLE: Final Notification for Transfer of Zener Filtering products from Hynix (Magna Chip) in Korea to ON Semiconductor Pocatello (ID) in United State.

PROPOSED FIRST SHIP DATE: 11-Jul-2012

AFFECTED CHANGE CATEGORY(S): ON Semiconductor Fab Site

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or YEW HEE SOON <y.soon@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office

ADDITIONAL RELIABILITY DATA: Available
Contact your local ON Semiconductor Sales Office or Francis Lualhati <francis.lualhati@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

ON Semiconductor is notifying customers of its plan to transfer fabrication of Zener Filtering products from Hynix (Magna Chip) located in Seoul, South Korea, to ON Semiconductor Fab 10 located in Pocatello, ID (USA).

Description of the change:

The transfer and qualification of the Zener Z1G process and the associated integrated circuits from the Hynix (Magna Chip) facility (South Korea) to the Fab 10 wafer fabrication site located in the Pocatello, Idaho.

The Fab 10 facility is an ON Semiconductor owned wafer fab that has been producing products since 2000 (formerly as AMI). Several existing technologies within ON Semiconductor's product families are currently sourced from Fab 10, including CMOS and LVFR products The Fab 10 Pocatello site is certified according to ISO9001:2008, 14001:2004, ISO/TS 16949:2009 and AS 9100B standards as well as MIL_PRF-38535, CTPAT and STACK.

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Qualification tests are designed to show that the reliability of transferred devices will continue to meet or exceed ON Semiconductor standards.

Devices listed in this final PCN should be transferred to ON Semiconductor Fab 10 in Pocatello starting Jul 2012. After 11 Jul 2012, customer may receive devices from either facility. Parts are identifiable by date code 1228 (YYWW).

RELIABILITY DATA SUMMARY:

Package: CSP
Qual Device: CM6305

Reliability Test Results:

Test	**Conditions**	**Interval**	**Results**
HTRB	TA=125°C, V=5 Volts	1008 hrs	0/240
HTSL	TA = 150°C	1008 hrs	0/240
UHAST	Ta=131C RH=85%, unbiased	1008 hrs	0/240
TC	Ta= -40 C to 125 C	10000 cyc	0/240
Autoclave	Ta=121C RH=100% ~15 psig	96 hrs	0/240
ESD IEC61000-4-2, Contact Discharge	± 8KV min		± 14KV
ESD IEC61000-4-2, Air Discharge	± 15KV min		± 15KV

ELECTRICAL CHARACTERISTIC SUMMARY:

Available upon request

CHANGED PART IDENTIFICATION:

There will be no changes to standard device markings. Normal assembly lot traceability codes will identify the wafer fab source.

List of affected General Parts:

CM6305
EMI6305